



Final Product Change Notification

202307002F01 : XSON8 - SOT833 Assembly and Test Transfer from "ATGD & ATSN" to ATBK

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 29, 2023 **Effective date:** Oct 27, 2023

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Management summary

This project is XSON8 - SOT833 Assembly & Test transfer from "ATGD & ATSN" to ATBK (NXP) for NCX2222GT, NTS0102GT, NTB0102GT, due to supply capacity shortage.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview

Description

- Assembly & Test transfer from "ATGD & ATSN" to ATBK (NXP);
- BOM change including bonding wire, die attach, molding compound, leadframe, pls. refer to PCN report for details;
- Marking content will be updated, pls. refer to PCN report for details;
- Tester update due to different test platform;

Note:

- Packing method will keep same as before;
- No change on die design, fab site/process, datasheet;

Reason

This project is XSON8 - SOT833 Assembly & Test transfer from "ATGD & ATSN" to ATBK (NXP) for NCX2222GT, NTS0102GT, NTB0102GT, due to supply capacity shortage.

Identification of Affected Products

Top Side Marking

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jan 08, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 28, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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